

# LF 1005 Series

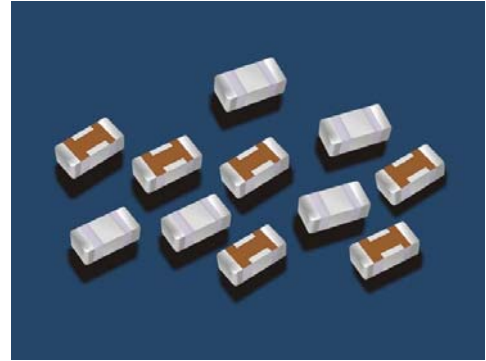
Multilayer Chip Low-Pass Filters

## Features

- ❖ Ultra small SMD type with low loss at pass-band and high attenuation at stop-band.
- ❖ RoHS compliant

## Applications

- ❖ Mobile communication systems, including GSM/CDMA/LTE phones, etc.



## Specifications

Part Number	Freq. Range (MHz)	Insertion Loss @ BW (dB)	VSWR @ BW	Frequency	Attenuation (dB)
<b>LF1005-K1R9DBB_</b>	1880 ~ 2025	0.6 max.	2.0 max. @ 1880 ~ 1920MHz	3760 ~ 4050MHz	26 min.
			1.7 max. @ 2010 ~ 2025MHz	5640 ~ 6075MHz	21 min.

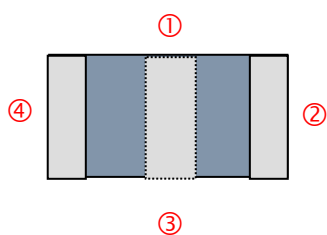
Q'ty/Reel (pcs) : 10,000  
 Operating Temperature Range : -40 ~ +85 °C  
 Storage Temperature Range : -40 ~ +85 °C  
 Storage Period : 12 months max.\*  
 Power Capacity : 500mW max.

## Part Number

LF   1005   -   K   1R9   DBB   □   /LF  
 ①   ②   ③   ④   ⑤   ⑥   ⑦

① Type	LF : Low-Pass Filter	② Dimensions ( L x W )	1.0 x 0.5 mm
③ Material Code	K	④ Frequency Range	1R9 = 1900MHz
⑤ Specification Code	DBB	⑥ Packaging	T: Tape & Reel B: Bulk
⑦ Soldering	/LF=lead-free		

## Terminal Configuration

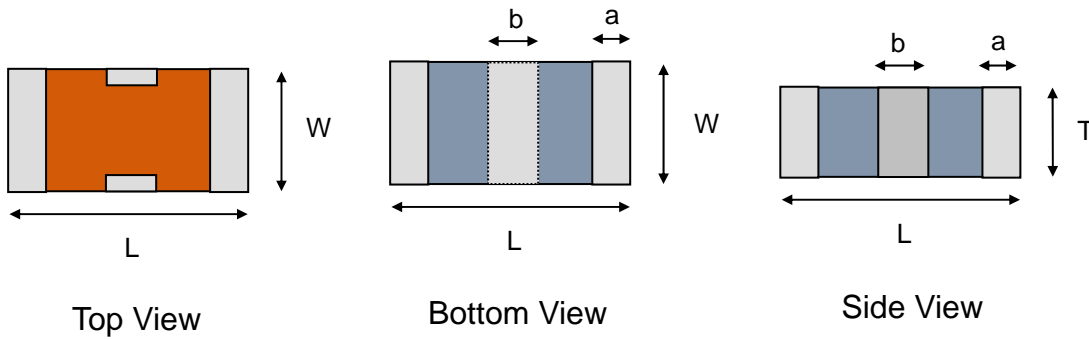


Bottom View

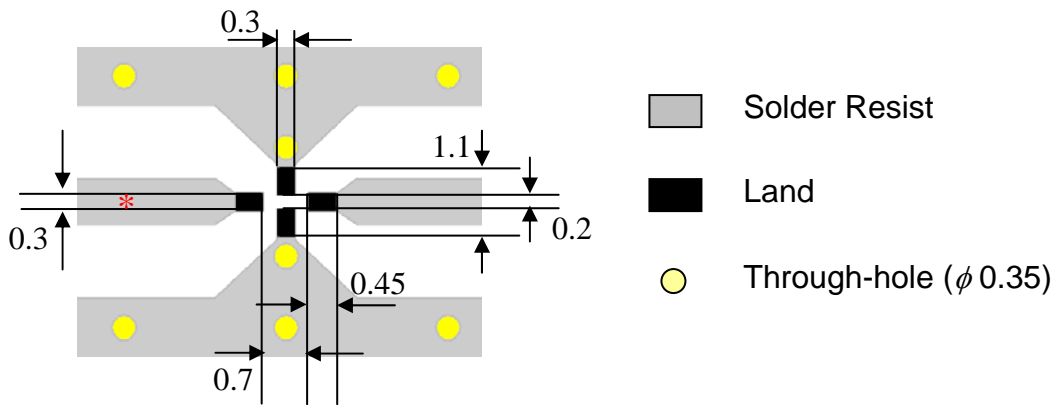
No.	Terminal Name	No.	Terminal Name
①	GND	③	GND
②	OUT	④	IN

## Dimensions and Recommended PC Board Pattern

Unit : mm

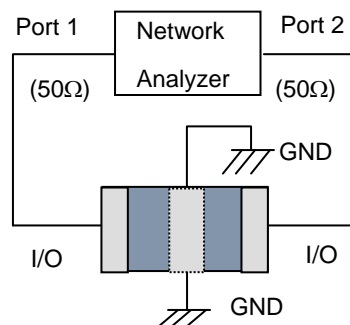


Mark	L	W	T	a	b
Dimensions	1.0 ± 0.05	0.5 ± 0.05	0.38 ± 0.05	0.18 ± 0.1	0.25 ± 0.1

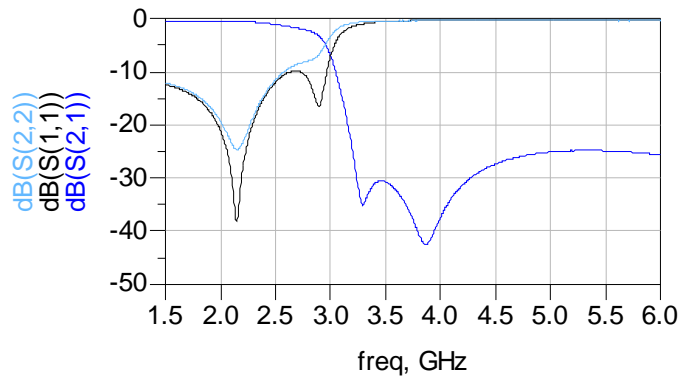


\* Line width should be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness.

## Measuring Diagram



## Electrical Characteristics (T=25°C)

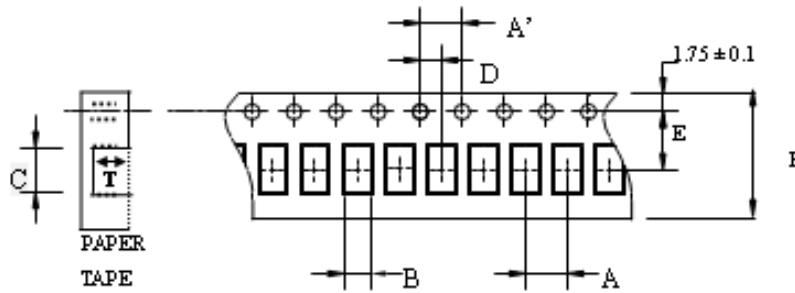


### Notes

- ❖ The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.

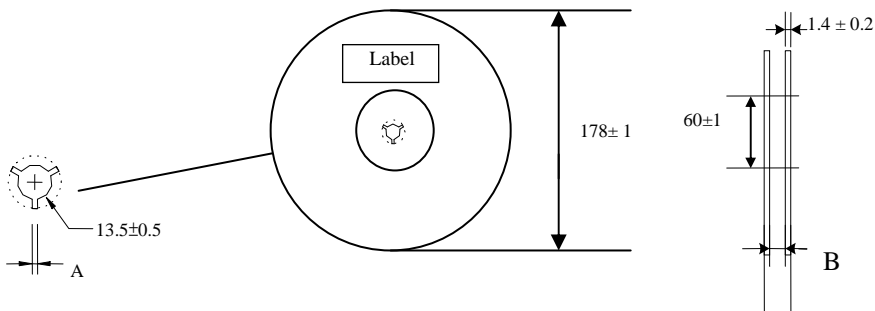
## Taping Specifications

### ❖Tape Dimensions (Unit: mm) & Quantity



Type	A	A'	B	C	D	E	F	T	Quantity/reel	Tape material
1005	2.0±	4.0±	0.62±	1.12±	2.0±	3.5±	8.0±	0.45±	10,000pcs	Paper
	0.05	0.1	0.03	0.03	0.05	0.05	0.1	0.03		

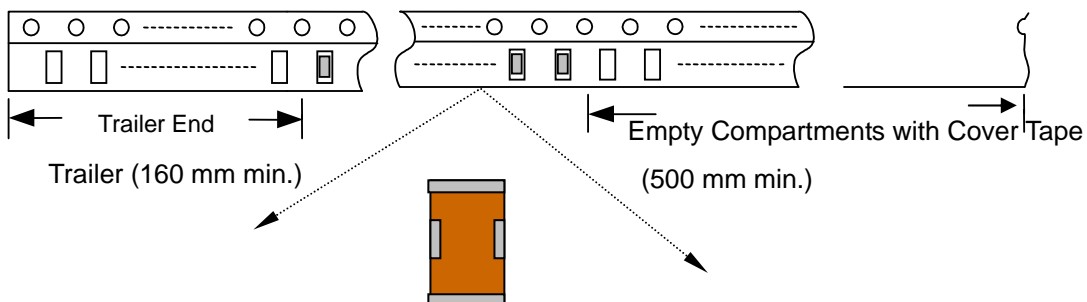
### ❖Reel Dimensions (Unit: mm)



Label: Customer's Name,  
ACX P/N, Q'ty, Date,  
ACX Corp.

Type	A	B
1005	2.3±0.5	9.0±0.3

### ❖Leader and Trailer Tape



❖ **Peel-off Force**



Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of  $300 \pm 10$  mm/min .

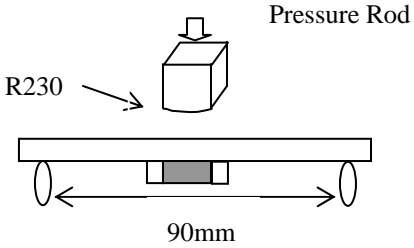
❖ **Storage Conditions**

- (1) Temperature: 5 ~35°C , relative humidity (RH): 45~75%.
- (2) Non-corrosive environment.

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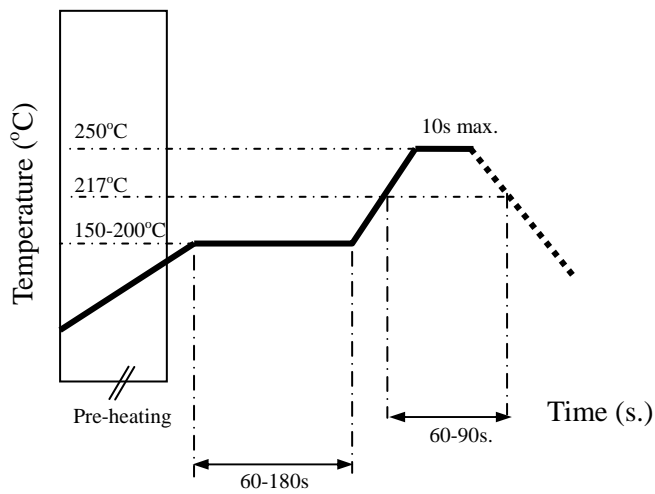
## Mechanical & Environmental Characteristics

Item	Requirements	Procedure
Solderability	<ol style="list-style-type: none"> <li>No apparent damage</li> <li>More than 75% of the terminal electrode shall be covered with new solder.</li> </ol>	<ol style="list-style-type: none"> <li>Preheat: <math>120 \pm 5^\circ\text{C}</math></li> <li>Solder: <math>245 \pm 5^\circ\text{C}</math> for <math>5 \pm 1</math> sec</li> </ol>
Soldering strength (Termination Adhesion)	<ol style="list-style-type: none"> <li>3N minimum</li> </ol>	<ol style="list-style-type: none"> <li>Solder specimen onto test jig.</li> <li>Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction</li> </ol>
Deflection (Substrate Bending)	<ol style="list-style-type: none"> <li>No apparent damage</li> <li>Fulfill the electrical specification</li> </ol>	<ol style="list-style-type: none"> <li>Solder specimen onto test jig (FR4, 0.8mm) using the recommend soldering profile.</li> <li>Apply a bending force of 2mm deflection</li> </ol> 
Heat/Humidity Resistance	<ol style="list-style-type: none"> <li>No apparent damage</li> <li>Fulfill the electrical specification after test</li> </ol>	<ol style="list-style-type: none"> <li>Temperature: <math>85 \pm 2^\circ\text{C}</math></li> <li>Humidity: 90% ~ 95% RH</li> <li>Duration: <math>1000 \pm 48</math>hrs</li> <li>Recovery: 1-2hrs</li> </ol>
Thermal shock (Temperature Cycle)	<ol style="list-style-type: none"> <li>No apparent damage</li> <li>Fulfill the electrical specification after test</li> </ol>	<ol style="list-style-type: none"> <li>One cycle/step 1 : <math>125 \pm 5^\circ\text{C}</math> for 30 min step 2 : <math>-40 \pm 5^\circ\text{C}</math> for 30 min</li> <li>No of cycles : 100</li> <li>Recovery: 1-2 hrs</li> </ol>
Low Temperature Resistance	<ol style="list-style-type: none"> <li>No apparent damage</li> <li>Fulfill the electrical specification after test</li> </ol>	<ol style="list-style-type: none"> <li>Temperature: <math>-40 \pm 5^\circ\text{C}</math></li> <li>Duration: <math>500 \pm 24</math>hrs</li> <li>Recovery: 1-2hrs</li> </ol>

## Soldering Conditions

### ❖ Typical Soldering Profile for Lead-free Process

Reflow Soldering :



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